AN3126

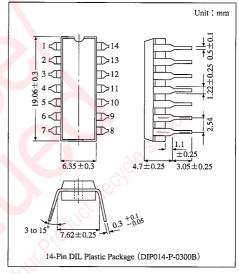
RF Modulator IC

Overview

The AN3126 is an integrated circuit designed for VHF-band RF modulator. Compared with our conventional IC (AN3125), the employment of a new circuit in the AN3126 reduces the number of external parts and provides enhanced sound and picture quality.

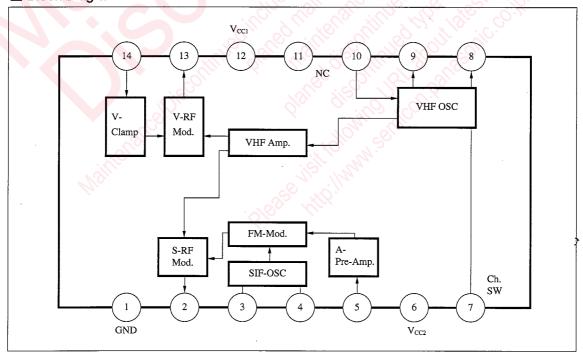
Features

- Operation on low voltage, V_{CC}=5V and low current, I_{CC}=18mA
- VHF oscillator has a large oscillation margin
- High-performance white clip circuit
- P/S ratio can be set by external resistor
- · Stabilized power supply built-in



ICs for VCR

Block Diagram



■ Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Supply voltage	V _{cc}	6	V	
Supply current	I_{CC}	42	mA	
Power dissipation	P _D	250	mW	
Operating ambient temperature	T_{opr}	-20 to +75	°C	
Storage temperature	T _{stg}	-55 to $+150$	C	

■ Recommended Operating Range (Ta=25°C)

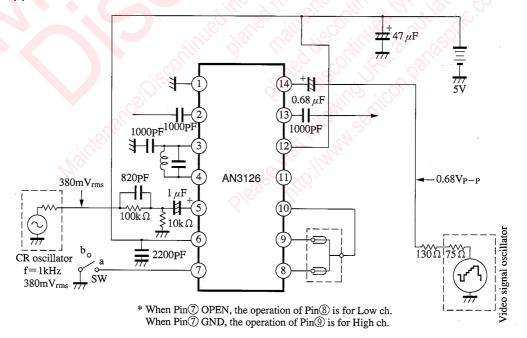
Parameter	Symbol	Range
Operating supply voltage range	V _{cc}	4.5V to 5.5V

■ Electrical Characteristics $(Ta=25^{\circ}C)$

Parameter	Symbol	Condition	min	typ	max	Unit
Current consumption	I_{tot}	+B=5V	13	18	23	mA
Video Circuit Characteristics				803	/	
Video carrier output level *	V _P	APL10, 50, 90m=75%	87	89	91	$dB\mu$
Maximum video modulation factor	m _{max}	Input 1.2V _{P-P}	90	95	. 99	%
Video modulation factor	m	APL10, 50, 90 Input 0.68V _{P-P}	70	75	80	%
Sync distortion	Sync	m=75%	-8.5		+4	%
Audio Circuit Characteristics		(0)		·		<u> </u>
Audio sub-carrier output level *	Vs	10 . O . 10°	82		86	dB
Audio FM modulation sesitivity	Δf_{FM}	Sin=380mVrms	±19.9		±31.3	kHz
Audio SN ratio	SNs		55	63	40,	dB

^{*} Based on the value measured at 75 Ω system, 2dB is added to the value measured at 50 Ω when measured at 50 Ω system.

Application Circuit



Pin Descriptions

Pin No.	Pin name	Typ. waveform	Description	I/O impedance	Equivalent circuit
1	GND		GND	_	
2	AUDIO RF OUT	84dBμ	Audio RF output pin (the audio FM signal is AM-modulated and output)	26Ω	2
3	4.5MHz TANK	3V	Audio tank coil connection pin.		3
4	4.5MHz TANK	1.4V _{PP}	Audio tank coil connection pin.		
5	AUDIO IN	0V f=1kHz 380 mVrms	Audio input pin,	20kΩ	5 20kΩ,2
6	V _{cc1}		Supply voltage 1.		
7	CH SW	1.5V	CH selector SW OPEN↔GND	30kΩ	7 30k Ω 30k Ω 30k Ω
8	SAW OUT1 (LOW CH)	3.9, 5V	SAW resonator output (LOW CH) pin	1kΩ	or 9
9	SAW OUT2 (HIGH CH)	5V, 3.9V	SAW resonator output (HIGH CH) pin	1kΩ	10
10	SAW IN	3.4V	SAW resonator input pin.	3kΩ	<u>+</u>
11	NC NC	<u> </u>	NC STATE OF THE PROPERTY OF TH	_	
12	V _{CC2}		Supply voltage 2.		
13	VIDEO RF OUT	89dBμ	Video RF output pin (the video signal is AM-modulated and outputted.)	26Ω	13 (1) (1)
14	VIDEO IN	3.3V 0.68V _{PP}	Video input pin.		14

■ Supplementary Explanation

• Reference Value for Design in Electrical Characteristics $(Ta=25^{\circ}C)$

Parameter	Symbol	Condition	min	typ	max	Unit
Video Circuit Characteristics				-		
DG	DG	m=75%	-5	+2	+5	%
DP	DP	m=75%	-5	-1	+5	0eg
Video modulation factor difference between channels	⊿m	ch1:m=75%	-2	0	+2	%
Audio Circuit Characteristics						
Audio FM modulation distortion I	THD1	Sin=380mVrms		0.2	1	%
Audio FM modulation distortion II	THD2	Sin=1300mVrms	\ <u> </u>	0.8	3	%
Audio buzz	Buzz	m=75%	52	58		dB

Note) The value in the above characteristics is not a guaranteed value, but reference one on design.

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